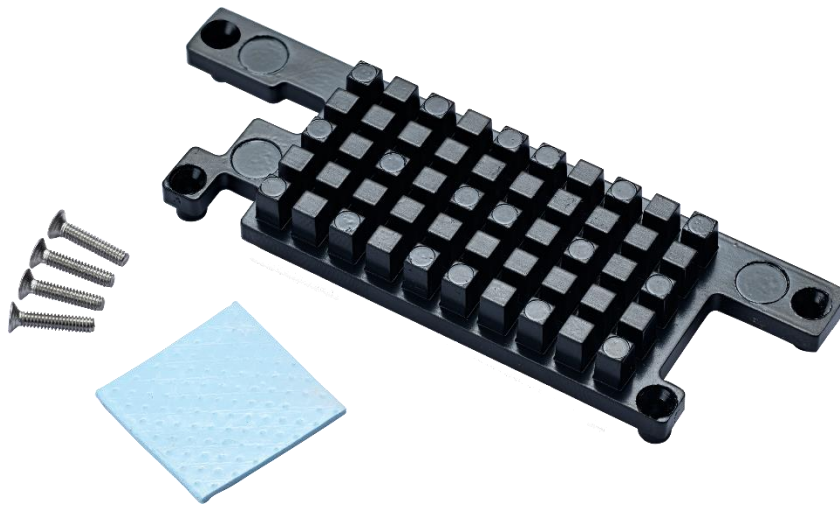




VARISCITE LTD

VHP-VS8M Heat Sink Kit For:
VAR-SOM-MX8M-PLUS, VAR-SOM-MX8M-MINI
VAR-SOM-MX8M-NANO



VARISCITE LTD.

VHP-VS8M Heat Sink

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1. Revision History

Revision	Date	Notes
1.00	May 04 2021	Initial – Preliminary

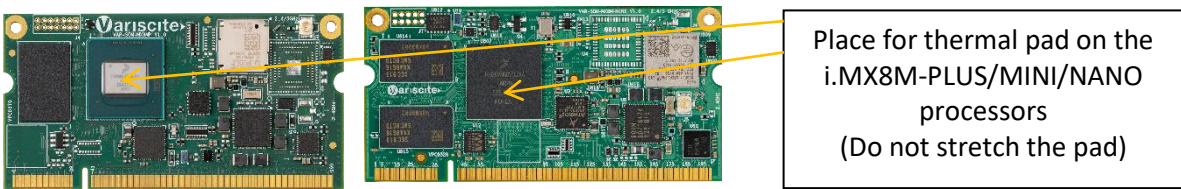
2. Heat Sink Kit Content

- 1 x heat sink
- 1 x thermal pad (fits VAR-SOM-MX8M-PLUS/MINI/NANO)
- 4 x M2/10mm screws (different screw drive types may be provided)

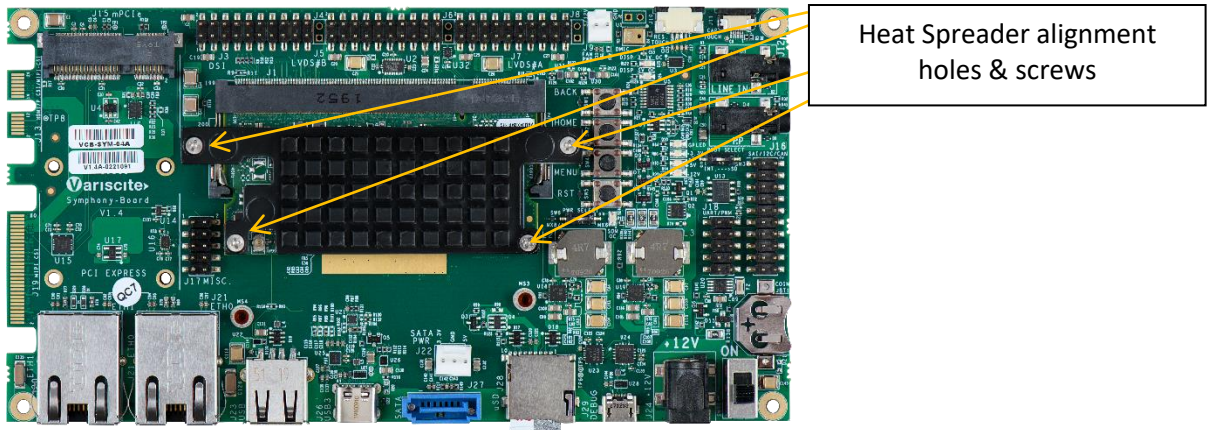
3. Heat Sink Assembly

3.1 Attach the thermal pad on top of the i.MX8M-PLUS/MINI/NANO processors in VAR-SOM-MX8M-PLUS/MINI/NANO.

Make sure that the two plastic covers, on both sides of thermal pads are removed before attaching the pad (**Please see note under section 3.4 for thermal paste option**).



3.2 Assemble the heat spreader on top side of VAR-SOM-MX8M-PLUS/MINI/NANO. Use the mechanical holes in order to align the heat spreader to VAR-SOM-MX8M-PLUS/MINI/NANO PCB.

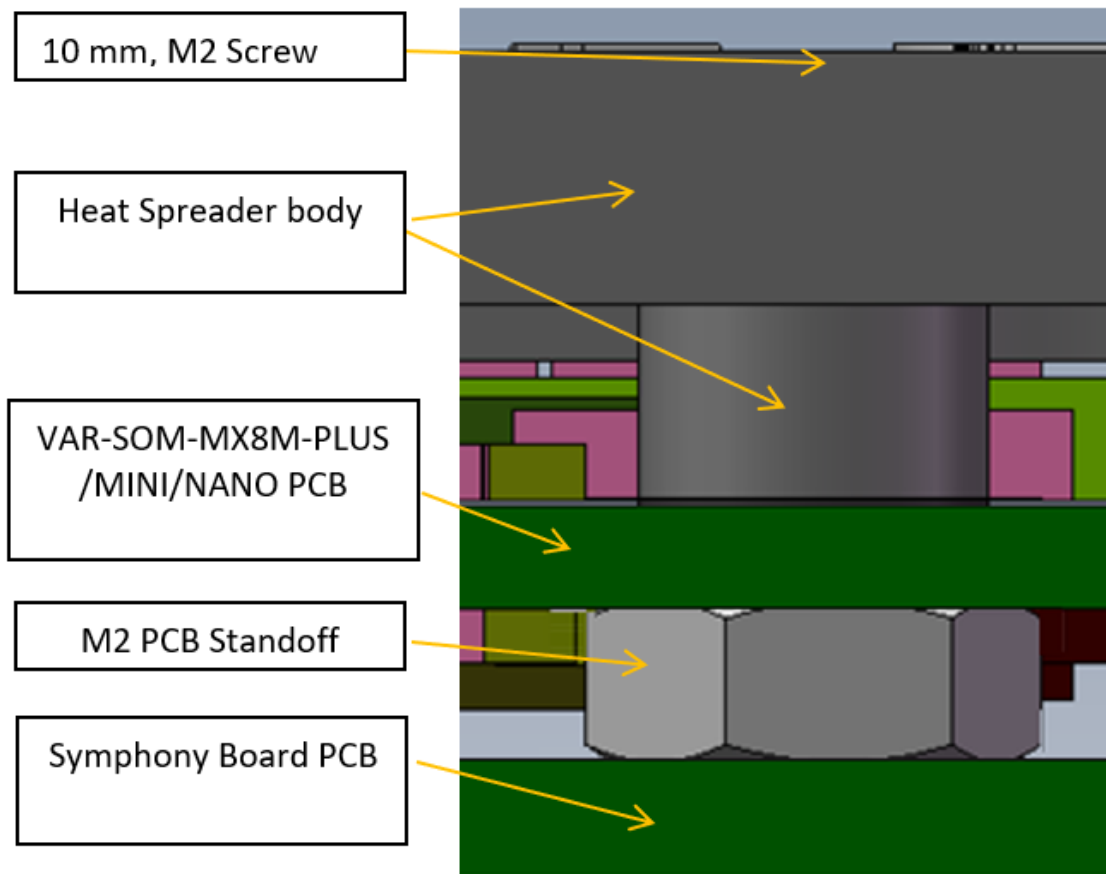


3.3 Insert the M2 screws from the heat spreader top side.

3.4 Tight the head spreader to the VAR-SOM-MX8M-PLUS/MINI/NANO using the supplied screws. Recommended torque for tightening the screws is $\sim 1\text{in-lb}$ ($\sim 0.113\text{N-m}$).

NOTE: due to tolerances of the related components (heat sink, thermal pad, PCB, i.MX8M processor) there might be a small gap between the heat sink's stands to the PCB itself. It is highly recommended before tightening all 4 nuts/screws to push the heat sink on top of the thermal pad so it will be squeezed on the processor. Only afterwards tighten the top two screws, then the bottom ones close to the SO-DIMM connector while paying attention when tightening the last screw that there is no extra pressure on the PCB that might cause it to deform. If you see extra pressure is created on the PCB, you should not tighten the screw all the way and use Loctite or similar glue to lock the screws. Another alternative is to use thermal paste (grease) instead of thermal pad which bridges the gap between the processor and the heat sink in different tolerances of the related components. The thermal paste should have similar thermal conductivity as the thermal pad, 6.0 watt/m-k (by JIS R2618 / ASTM D2326 standard).

Heat Sink assembly sketch



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